

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	"20050079664"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/08/28 15:20
S2	8	"6335501"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/11 17:58
S3	22	"6103597"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/11 18:51
S4	6	((("6355501") or ("6335501") or ("6103597") or ("6221738") or ("6100166") or ("6184111")),PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/11 18:54
S5	294	faris-sadeg-m.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/13 17:47
S6	12	S5 and substrate and strong and weak and bond\$4 and remov\$4 and vertical\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/13 18:16
S7	1	"10719663"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/13 18:16
S8	6	("4903118" "6159323" "6316333" "6342433" "6355501" "6777312").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 18:16
S9	11	("4727047" "5371037" "5650353" "5811348" "5854123" "5856229" "5897743" "6020252" "6091112" "6107213" "6140210").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 18:23
S10	4	("4727047" "5250460" "5362638" "5459081").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 18:36
S11	45	("5811348").URPN.	USPAT	OR	ON	2005/10/13 18:38
S12	45	("5811348").URPN.	USPAT	OR	ON	2005/10/13 18:45
S13	77	"6084781"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:01
S14	70	S13 and (remov\$3 or detact\$3 or depond\$3 or de-bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:09
S15	0	S14 and (buried near2 \$2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:03

EAST Search History

S16	32	S14 and (\$2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:04
S17	32	S16 and (substrate or wafer or base or board) and (contact\$3 or electrode or pad or bump or terminal)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:05
S18	31	S17 and (@ad<"20021120" or @rlad<"20021120")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:20
S19	22255	(substrate or wafer or board or base) and (remov\$3 or detach\$3 or depond\$3 or de-bond\$3) and ((buried or dop\$3 or implant\$4) near2 \$2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:33
S20	1926	438/455-458.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:18
S21	1099	257/e21.567-e21.568.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:20
S22	19162	(S19 S20 S21) and (@ad<"20021120" or @rlad<"20021120") and (remov\$3 or detach\$3 or depond\$3 or de-bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:21
S23	38	(S19 S20 S21) and (@ad<"20021120" or @rlad<"20021120") and (detach\$3 or depond\$3 or de-bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:52
S24	601	(S22 not S23) and (strong\$3 near2 (attach\$4 or bond\$3 or stick\$3 or past\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:36
S25	88	S24 and (weak\$3 near2 (attach\$4 or bond\$3 or stick\$3 or past\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:35
S26	57	S25 and (implant\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:31
S27	37	S25 and (implant\$4 with \$2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:53
S28	1	"6956268"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 13:37

EAST Search History

S29	1171	438/455.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:24
S30	88	H01L21/30.IPC.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:24
S31	730	((substrate or wafer or board or base) and (remov\$3 or detach\$3 or depond\$3 or de-bond\$3 or split\$3) and ((buried or dop\$3 or implant\$4) near2 \$2oxide)).clm.	US-PGPUB	OR	ON	2006/03/30 14:50
S32	724	S31 not (S18 S23 S27 S28 S30)	US-PGPUB	OR	ON	2006/03/30 14:51
S33	7	S24 and (weak\$3 near2 (attach\$4 or bond\$3 or stick\$3 or past\$3)).clm.	US-PGPUB	OR	ON	2006/03/30 14:36
S34	1	S32 and (strong\$3 near2 (attach\$4 or bond\$3 or stick\$3 or past\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:36
S35	1634	((substrate or wafer or board or base) with (handl\$3 or donor\$3)) and (remov\$3 or detach\$3 or depond\$3 or de-bond\$3 or split\$3) and ((buried or dop\$3 or implant\$4) near2 \$2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:51
S36	97	(S35 not (S18 S23 S27 S28 S30 S34 S33)) and (@ad<"20021120" or @rlad<"20021120") and (detach\$3 or depond\$3 or de-bond\$3 or split\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:52
S37	49	S36 and (implant\$4 with \$2oxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/03/30 14:53
S39	129	("4309225" "4370176" "4371421" "4471003" "4479846" "4500563" "4585945" "4816420" "4837182" "4846931" "4883561" "5273616" "5362682" "5374564" "5453153" "5559043" "5588994" "5676752" "5710057" "5714395" "5793115" "5845123" "5877070" "5882987" "5897939" "5909627" "5920764" "5933750" "5976953" "5985688" "5993677" "5994207" "0006020" "6027988" "6033974" "6054363" "6054370" "6059877" "6071795" "6103597" "6137110" "6146979" "6155909" "6159323" "6159824" "6159825" "6162705" "6184060" "6184111" "6187110" "6190937" "6190998" "6191007" "6204151" "6214733" "6221738" "6221740" "6221774" "6225190" "6225192" "6232136" "6309945" "6387736").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:37
S40	107	S39 and (bond\$4 rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:15
S41	98	S40 and (depond\$4 detach\$4 remov\$4 separat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:36
S42	1	S41 and strong and week	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:28

EAST Search History

S43	46	S41 and ((buri\$3 or embed\$4) near2 (\$2oxide insulat\$3 dielectric) or "SOI")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:36
S44	54	"6355501"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:36
S45	28	S44 and (depond\$4 detach\$4 remov\$4 separat\$4) and ((buri\$3 or embed\$4) near2 (\$2oxide insulat\$3 dielectric) or "SOI")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:37
S46	7	S45 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 18:24
S47	46	S43 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 17:41
S48	1	"10719663"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:51
S49	4205	257/415,417-420,619,620,e21.567,e21.568e21.569,e21.571.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:52
S50	4758	438/48-50,415,417,418,455-459.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:53
S51	107	H01L29/82.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:54
S52	227	H01L21/30.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 19:56
S53	1289	438/455.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:12

EAST Search History

S54	910	438/458.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:15
S55	6249	(S49 S50) and ((bond\$4 rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) same (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 20:17
S56	4208	257/415,417-420,619,620,e21.567,e21.568e21.569,e21.571.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:56
S57	4763	438/48-50,415,417,418,455-459.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:56
S58	6257	(S56 S57) and ((bond\$4 rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) same (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:58
S59	5725	S58 and ((rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) same (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 13:38
S60	5011	S58 and ((rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:15
S61	3736	S60 and (@ad<"20021120" @rlad<"20021120")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 11:59
S62	1616	S61 and ((strong or streng\$5 or great\$3 high\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:09
S63	1029	S62 and ((week\$4 weak\$4 low\$3 less\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:03
S64	1123	S61 and (("SOI" or ((buried embed\$3) with (\$2oxide dielectric insulat\$3))) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:10

EAST Search History

S65	445	S63 and S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:09
S66	359	S65 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:11
S67	309	S66 and (("SOI" or ((buried embed\$3) near3 (\$2oxide dielectric insulat\$3))) near3 (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:14
S68	291	S67 and ((rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) near5 (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:16
S69	285	S67 and ((rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) near3 (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:19
S70	259	S69 and ((rebond\$4 depond\$4 detach\$4 remov\$4 separat\$4) with (semiconduct\$4 \$4silicon acti\$4) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:02
S71	32	S68 not S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:47
S72	50	S67 not S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:40
S73	4	"6956268"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:30
S74	21726	((((depond\$4 detach\$4 split\$4 remov\$4 separat\$4) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3)) and ((week\$4 weak\$4 low\$3 less\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:14
S75	3822	S74 and ((strong or streng\$5 or great\$3 high\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:48

EAST Search History

S76	53	S75 and ("SOI" or ((buried embed\$3) with (\$2oxide dielectric insulat\$3))) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:10
S77	10221	((depond\$4 detach\$4 split\$4 remov\$4 separat\$4 peel\$4) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3)) and ((weak\$4 low\$3 less\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3)) and ("SOI" (silicon adj2 insulat\$4) ((buried embed\$3) near2 (\$2oxide dielectric insulat\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:59

EAST Search History

S78	259	(US-20060189096-\$ or US-20050258489-\$ or US-20050042840-\$ or US-20050029594-\$ or US-20050029592-\$ or US-20040253458-\$ or US-20040171233-\$ or US-20040169225-\$ or US-20040157402-\$ or US-20040102021-\$ or US-20040082146-\$ or US-20040067621-\$ or US-20040063322-\$ or US-20040048446-\$ or US-20030203547-\$ or US-20030190794-\$ or US-20030087503-\$ or US-20030045019-\$ or US-20030020096-\$ or US-20030017679-\$ or US-20030008477-\$ or US-20020185684-\$ or US-20020132451-\$ or US-20020127820-\$ or US-20020121655-\$ or US-20020102816-\$).did. or (US-20020094668-\$ or US-20020093047-\$ or US-20020089016-\$ or US-20020070291-\$ or US-20020068419-\$ or US-20020045327-\$ or US-20020024152-\$ or US-20020016020-\$ or US-20020004286-\$ or US-20010055863-\$ or US-20010046746-\$ or US-20010041423-\$ or US-20010029060-\$ or US-20010019153-\$ or US-20010016401-\$ or US-20010007367-\$ or US-20010003668-\$).did. or (US-7067396-\$ or US-7045439-\$ or US-7014748-\$ or US-6993826-\$ or US-6979629-\$ or US-6936482-\$ or US-6900114-\$ or US-6895136-\$ or US-6890835-\$ or US-6881644-\$ or US-6860963-\$ or US-6848306-\$ or US-6846723-\$ or US-6846718-\$ or US-6844243-\$ or US-6838301-\$ or US-6809009-\$ or US-6774435-\$ or US-6774010-\$ or US-6773951-\$ or US-6773534-\$ or US-6759282-\$ or US-6746559-\$ or US-6709966-\$ or US-6680260-\$ or US-6672358-\$).did. or (US-6670212-\$ or US-6656271-\$ or US-6653206-\$ or US-6653205-\$ or US-6639327-\$ or US-6638834-\$ or US-6635552-\$ or US-6630713-\$ or US-6624047-\$ or US-6624046-\$ or US-6617657-\$ or US-6609553-\$ or US-6605518-\$ or US-6600231-\$ or US-6597039-\$ or US-6596610-\$ or US-6593211-\$ or US-6569748-\$ or US-6566233-\$ or US-6544837-\$ or US-6540861-\$ or US-6538330-\$ or US-6537846-\$ or US-6534384-\$ or US-6534383-\$ or US-6534382-\$ or US-6534381-\$).did. or (US-6534380-\$ or US-6527031-\$ or US-6524935-\$ or US-6521078-\$ or US-6513564-\$ or US-6498073-\$ or US-6492682-\$ or US-6486008-\$ or US-6482725-\$ or US-6475323-\$ or US-6475072-\$ or US-6472711-\$ or US-6472244-\$ or US-6468923-\$ or US-6468663-\$ or US-6461939-\$ or US-6455398-\$ or US-6436226-\$ or US-6429095-\$ or US-6428620-\$ or US-6427748-\$ or US-6426270-\$ or US-6423613-\$ or US-6423563-\$ or US-6418999-\$ or US-6417108-\$ or US-6410436-\$).did. or (US-6399516-\$ or US-6382292-\$ or US-6362077-\$ or US-6352909-\$ or US-6346735-\$ or US-6346435-\$ or US-6342433-\$ or US-6331473-\$ or US-6329265-\$ or US-6328796-\$ or US-6326285-\$ or US-6326279-\$ or US-6323108-\$ or US-6313012-\$ or US-6312797-\$ or US-6309950-\$ or US-6309945-\$ or US-6306730-\$ or US-6306729-\$ or US-6303977-\$ or US-6291315-\$ or US-6287885-\$ or US-6284629-\$ or US-6284628-\$ or US-6281551-\$ or US-6281033-\$ or US-6265238-\$).did. or (US-6263941-\$ or US-6255731-\$ or US-6248610-\$ or US-6246068-\$ or US-6245645-\$ or US-6242324-\$ or US-6239004-\$ or US-6225192-\$ or US-6224668-\$ or US-6221738-\$ or US-6211041-\$ or US-6200878-\$ or US-6194290-\$ or US-6191007-\$ or US-6171932-\$ or US-6156624-\$ or US-6153495-\$ or US-6150239-\$ or US-6143629-\$ or US-6143628-\$ or US-6140210-\$ or US-6140209-\$ or US-6121117-\$ or US-6110391-\$ or US-6100570-\$ or US-6100166-\$ or US-6100165-\$).did. or (US-6093623-\$ or US-6093577-\$ or US-6063686-\$ or US-6057212-\$ or US-6054371-\$ or US-6051855-\$ or US-6020215-\$ or US-6008110-\$ or US-6004865-\$ or US-5998281-\$ or US-5994750-\$ or US-5980633-\$ or US-5976953-\$ or US-5966620-\$ or US-5963785-\$ or US-5937312-\$ or US-5923637-\$ or US-5918139-\$ or US-5880010-\$ or US-5877070-\$ or US-5876497-\$ or US-5869387-\$ or US-5869386-\$ or US-5854123-\$ or US-5849627-\$ or US-5843832-\$ or US-5840616-\$).did. or (US-5834812-\$ or US-5773355-\$ or US-5769991-\$ or US-5769903-\$ or US-5750080-\$ or US-5728824-\$ or US-5721162-\$ or US-5710057-\$ or US-5705421-\$ or US-5698264-\$ or US-5698245-\$ or US-5698232-\$ or	US-PGPUB; USPAT	OR	ON	2006/08/29 17:47
8/30/2006 1:24:00 C:\Documents and Settings\onguyen\My Documents\EA\10719663.wsp					Page 8	

EAST Search History

S79	50	(US-20060125058-\$ or US-20050059218-\$ or US-20050026339-\$ or US-20050009288-\$ or US-20040253794-\$ or US-20040229443-\$ or US-20040081805-\$ or US-20030155568-\$ or US-20030148549-\$ or US-20020119640-\$).did. or (US-7081657-\$ or US-7029993-\$ or US-6716722-\$ or US-6554046-\$ or US-6538296-\$ or US-6497763-\$ or US-6388290-\$ or US-6335535-\$ or US-6242817-\$ or US-6225190-\$ or US-6221740-\$ or US-6198159-\$ or US-6171931-\$ or US-6091112-\$ or US-6060336-\$ or US-6013935-\$ or US-5985681-\$ or US-5969401-\$ or US-5915193-\$ or US-5882532-\$ or US-5855693-\$ or US-5804494-\$ or US-5650042-\$ or US-5569620-\$ or US-5556503-\$ or US-5413955-\$).did. or (US-5407856-\$ or US-5387555-\$ or US-5266824-\$ or US-5264395-\$ or US-5258318-\$ or US-5227339-\$ or US-5084419-\$ or US-5071785-\$ or US-5034343-\$ or US-5032544-\$ or US-4962879-\$ or US-4883215-\$ or US-4826787-\$ or US-4638552-\$).did.	US-PGPUB; USPAT	OR	ON	2006/08/29 17:47
S80	32	(US-20050059218-\$ or US-20050009288-\$ or US-20040253794-\$ or US-20040229443-\$ or US-20040081805-\$ or US-20030155568-\$).did. or (US-7081657-\$ or US-7029993-\$ or US-6716722-\$ or US-6554046-\$ or US-6497763-\$ or US-6388290-\$ or US-6335535-\$ or US-6225190-\$ or US-6221740-\$ or US-6198159-\$ or US-6013935-\$ or US-5882532-\$ or US-5804494-\$ or US-5569620-\$ or US-5413955-\$ or US-5407856-\$ or US-5387555-\$ or US-5266824-\$ or US-5258318-\$ or US-5227339-\$ or US-5071785-\$ or US-5034343-\$ or US-5032544-\$ or US-4962879-\$ or US-4883215-\$ or US-4826787-\$).did.	US-PGPUB; USPAT	OR	ON	2006/08/29 17:47
S81	6278	S77 and ((strong or streng\$5 or great\$3 high\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:49
S82	5930	S81 not (S76 S78 S79 S80)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:49
S83	3153	S82 and (@ad<"20010912" @rlad<"20010912")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:49
S85	2525	S83 and ((depond\$4 detach\$4 split\$4 remov\$4 separat\$4 peel\$4) with (semiconduct\$4 \$4silicon device "IC" die chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:55
S87	1725	S85 and ((depond\$4 detach\$4 split\$4 remov\$4 separat\$4) with (semiconduct\$4 \$4silicon) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 17:58
S88	510	S87 and ((weak\$4 low\$3 less\$3) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3) with (chip die "IC" device))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 18:01

EAST Search History

S89	374	S88 and ((die chip "IC" device) with (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3) with (substrate wafer board base "PCB" "PWB" carrier))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 18:03
S90	63	("4309225" "4370176" "4371421" "4471003" "4479846" "4500563" "4585945" "4816420" "4837182" "4846931" "4883561" "5273616" "5362682" "5374564" "5453153" "5559043" "5588994" "5676752" "5710057" "5714395" "5793115" "5845123" "5877070" "5882987" "5897939" "5909627" "5920764" "5933750" "5976953" "5985688" "5993677" "5994207" "6020252" "6027988" "6033974" "6054363" "6054370" "6059877" "6071795" "6103597" "6137110" "6146979" "6155909" "6159323" "6159824" "6159825" "6162705" "6184060" "6184111" "6187110" "6190937" "6190998" "6191007" "6204151" "6214733" "6221738" "6221740" "6221774" "6225190" "6225192" "6232136" "6309945" "6387736").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/29 18:33
S91	136	S88 not S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 18:46
S92	16	"6342433"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:13
S93	13	S92 and ((depond\$4 detach\$4 split\$4 remov\$4 separat\$4) with (substrate wafer carrier board base support\$3 handl\$4 donor\$3)) and (bond\$4 glue\$4 stick\$4 past\$4 attach\$4 adhes\$4 coupl\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:19